

2SK2591

Silicon N Channel MOS FET

Application

High speed power switching

Features

- Low on-resistance
 - High speed switching
 - Low drive current
 - No secondary breakdown
 - Suitable for switching regulator and DC-DC converter

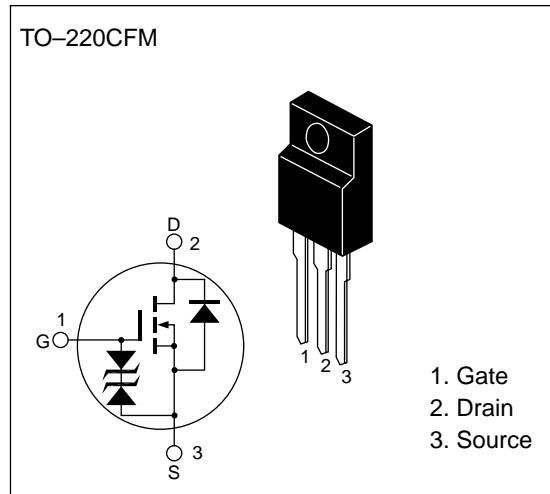


Table 1 Absolute Maximum Ratings (Ta = 25°C)

Drain to source voltage	V_{DSS}	500	V
Gate to source voltage	V_{GSS}	± 30	V
Drain current	I_D	8	A
Drain peak current	$I_{D(\text{pulse})}^*$	32	A
Body-drain diode reverse drain current	I_{DR}	8	A
Channel dissipation	P_{ch}^{**}	35	W
Channel temperature	T_{ch}	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

* PW \leq 10 μ s, duty cycle \leq 1 %

** Value at Tc = 25 °C

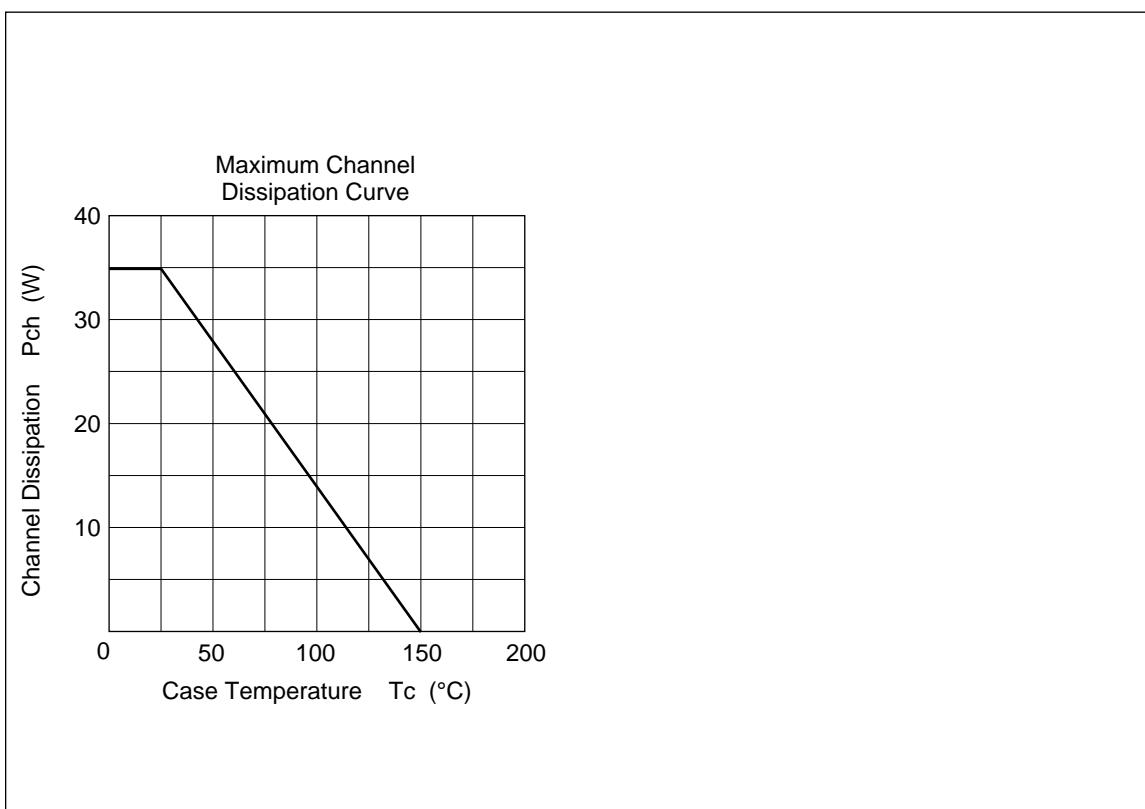
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Table 2 Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Drain to source breakdown voltage	V _{(BR)DSS}	500	—	—	V	I _D = 10 mA, V _{GS} = 0
Gate to source breakdown voltage	V _{(BR)GSS}	±30	—	—	V	I _G = ±100 µA, V _{DS} = 0
Gate to source leak current	I _{GSS}	—	—	±10	µA	V _{GS} = ±25 V, V _{DS} = 0
Zero gate voltage drain current	I _{DSS}	—	—	-250	µA	V _{DS} = 500 V, V _{GS} = 0
Gate to source cutoff voltage	V _{GS(off)}	2.0	—	-3.0	V	I _D = 1 mA, V _{DS} = 10 V
Static drain to source on state resistance	R _{DS(on)}	—	0.45	0.60	Ω	I _D = 4 A V _{GS} = 10 V *
Forward transfer admittance	y _{fs}	5.0	7.5	—	S	I _D = 4 A V _{DS} = 10 V *
Input capacitance	C _{iss}	—	1450	—	pF	V _{DS} = 10 V
Output capacitance	C _{oss}	—	410	—	pF	V _{GS} = 0
Reverse transfer capacitance	C _{rss}	—	55	—	pF	f = 1 MHz
Turn-on delay time	t _{d(on)}	—	20	—	ns	I _D = 4 A
Rise time	t _r	—	55	—	ns	V _{GS} = 10 V
Turn-off delay time	t _{d(off)}	—	130	—	ns	R _L = 5Ω
Fall time	t _f	—	50	—	ns	
Body-drain diode forward voltage	V _{DF}	—	0.9	—	V	I _F = 8 A, V _{GS} = 0
Body-drain diode reverse recovery time	t _{rr}	—	380	—	ns	I _F = 8 A, V _{GS} = 0, dI _F / dt = 100 A / µs

* Pulse Test

See characteristics curves of 2SK1166



Package Dimensions

Unit : mm

